

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6202298".pn.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 07:25
L8	54	("2734154"   "4034468"   "4034469"   "4254431"   "4299715"   "4323914"   "4398975"   "4435611"   "4466483"   "4473113"   "4607277"   "4806111"   "4915167"   "4966142"   "5011787"   "5031308"   "5037312"   "5056706"   "5071787"   "5074947"   "5086558"   "5097387"   "5131582"   "5148141"   "5148265"   "5148266"   "5164566"   "5170930"   "5196371"   "5198189"   "5223747"   "5237130"   "5323294"   "5325265"   "5328087"   "5445308"   "5455390"   "5459352"   "5542602"   "5553769"   "5557501"   "5561590"   "5572404"   "5651179"   "5658831"   "5688721"   "5720100"   "5808874"   "5819406"   "5920125"   "5975408"   "6000127"). PN. OR ("6202298"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 07:34
L12	1	8 and (permanent or remov\$3) and (solder with mask)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 07:34

L13	9	8 and mask	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 07:36
L14	1	"6437240".pn. and mask	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 07:37
L15	1	"6846700".pn. and mask	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 07:39
L19	1	electronic near50 assembly and (forming or formed or form) near50 (removable or remove or removed or removing or permanent) near50 solder near50 mask near50 conductive near50 contact near50 pad	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 08:04
L20	18	("3096466"   "3335327"   "3393449"   "3644792"). PN. OR ("3771101"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 08:02

L23	13	(forming or formed or form) near50 (removable or remove or removed or removing or permanent) near50 solder near50 mask near50 conductive near50 contact near50 pad	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 08:57
L24	947	228/179.1.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 09:22
L25	975	228/175.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 08:58
L26	1207	228/180.22.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 08:59
L27	3047	24 or 25 or 26	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 08:59
L28	1917	24 or 25 or 26	US-PGPU B; USPAT	OR	ON	2005/09/23 08:59

L29	3047	24 or 25 or 26	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T	OR	ON	2005/09/23 09:00
L32	9	29 and solder near50( mask or resist) and remov\$3 and reflow and vias and (signal or power or ground) near50(plane or interconnect\$3)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T	OR	ON	2005/09/23 09:16
L33	15	24 and (solder near50 mask) and reflow	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 09:31
L34	214	29 and (solder near50 mask) and reflow and(ball or bump)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 09:40
L35	15	("5471090"   "5663594"   "5859474"   "5895554"   "5917149"   "5951304"). PN. OR ("6078505"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 11:02
L36	1	"20010013654"	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 11:03

L41	1	36 and mask and ball and ground and power and signal	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 11:08
L44	4	("2001/0013654").URPN.	USPAT	OR	ON	2005/09/23 11:10
L45	47	("20010013654"   "20020008314"   "20020070443"   "20020158334"   "5055532"   "5105257"   "5327012"   "5346858"   "5353498"   "5355283"   "5422513"   "5497033"   "5503286"   "5523622"   "5527741"   "5608262"   "5701032"   "5703400"   "5707894"   "5745984"   "5798567"   "5844317"   "5864470"   "6014317"   "6049465"   "6060777"   "6084297"   "6084777"   "6130478"   "6153448"   "6154366"   "6162652"   "6222246"   "6239482"   "6242282"   "6249044"   "6255737"   "6271469"   "6284566"   "6287893"   "6291775"   "6333565"   "6388333"   "6388337"   "6396148"   "6590291"   "6621155").PN. OR ("6894399").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 11:11
L46	5	45 and mask and ball and power and signal and ground	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 11:15
L47	4	45 and mask and reflow and ball and power and signal and ground	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 11:15

L48	261	("4792646"   "5136366"   "5153385"   "5241133"). PN. OR ("5355283"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 11:40
L50	11	((("6555761") or ("6933449") or ("6884939") or ("6774310") or ("6486589") or ("6627822") or ("6730860") or ("6818155") or ("6803527") or ("6875367") or ("6461891"))).PN.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/09/23 11:47
L51	1	("20030218235").PN. OR ("6884939").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 11:49
L52	1	("20030218235").PN. OR ("6884939").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 12:33
L53	15	("4861941"   "5088007"   "5686699"   "5786630"   "5842877"   "5847936"   "5973929"   "6064113"   "6191475"   "6198635"   "6346679"   "6388890"   "6448639"   "6449169"   "6479758").PN. OR ("6730860").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 12:33
L54	65	("5191174"   "5400220"   "5450283"   "5535101"   "5598036"   "5615477"). PN. OR ("5847936"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 13:02
L55	98310	"361"/\$	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 13:02

L56	59771	"174"/\$	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 13:02
L57	137045	55 or 56	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 13:03
L60	403	57 and (solder near50 mask) and ((signal or ground or power) and alternat\$3 or parallel) and form\$3 and (capacitor or capacitance)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 13:09
L61	92	60 and reflow and contact near50 (pad or land)and heat\$3 and remov\$3	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 13:11
L62	15	("4861941"   "5088007"   "5686699"   "5786630"   "5842877"   "5847936"   "5973929"   "6064113"   "6191475"   "6198635"   "6346679"   "6388890"   "6448639"   "6449169"   "6479758").PN. OR ("6730860").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 15:32

L65	1952	62 or (solder near50 (mask or resist) near50 (remov\$3 or clean\$3 or dislodg\$3)) and (reflow or heat\$3)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 15:35
L66	251	65 and (signal or power or ground) near50 ( via or bar or plane)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 15:39
L67	22	("4573261"   "4668533"   "4748453"   "4767489"   "4824010"   "4963882"   "4999646"   "5207115"   "5239312"   "5270368"   "5356658"   "5560534"   "5587730"   "5590455"   "5637426"   "5640183"   "5790150"   "5793392"   "5984455"   "6000124"   "6076910"   "6439681"). PN. OR ("6754551"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 16:13
L68	6	("4854040").URPN.	USPAT	OR	ON	2005/09/23 16:26
S23	663	228/56.3.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 13:47



S24	103	228/111.5.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/21 16:16
S25	1207	228/180.22.ccls.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/21 16:16
S26	1926	S23 or S24 or S25	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/21 16:17
S27	48	S26 and solder near50(bump or ball) near50 mask near50 remov\$3 naer50 permanent near50 (contact near20 pad) near50 exposed near50 plurality near20 (capacitor or land) near50 solidify\$3 near50 melt\$3	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/21 16:49
S28	4	("5034345"   "5376584"   "5656863"   "5660321"). PN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/21 16:26

S29	1	S26 and vias and (contact near20 pad) and (permanent or remov\$3) near20 (solder near20 mask) and (power or ground) near20 plane near20 separat\$3 near50 layers	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/21 16:54
S30	9	S26 and vias and (contact near20 pad) and (permanent or remov\$3) and (solder near20 mask) and (power or ground) and plane and separat\$3 and layers	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/21 16:54
S31	83	("3621564"   "3645392"   "3719981"   "4119480"   "4311267"   "4722470"   "4752027"   "4825034"   "4914814"   "5024372"   "5057969"   "5118027"   "5133495"   "5145104"   "5196726"   "5203075"   "5219117"   "5261155"   "5261593"   "5275970"   "5341564"   "5346118"   "5388327"   "5468681"   "5492266"   "5539333"   "5542601"   "5545465"   "5564617"   "5586715"   "5597469"   "5607099"   "5623506"   "5643831"   "5658827").PN. OR ("5872051").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/21 17:00
S32	79	("3214827"   "3379937"   "3380155"   "4545610"   "4565314"   "4818728"   "4836435"   "4998665"   "5006920"   "5007163"   "5075965"   "5214308"   "5250469").PN. OR ("5341564").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/21 17:25
S33	18	("5341564"   "5952718").PN. OR ("6190940").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/21 17:34

S34	26	package and substrate and printed and circuit and (power or ground or signal) and ( vias or plane or pad) and solder and connection and mask and transmit\$3 and communicat\$3 and conduct\$3 and path and heat\$3 and cool\$3 and (solidify or solidification or solidified) and current	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 14:01
S35	9	package and substrate and printed and circuit and (power or ground or signal) near50 ( vias or plane or pad) and (solder near50 mask) and transmit\$3 and (conduct\$3 near50 path) and heat\$3 and cool\$3 and (solidify or solidification or solidified)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 14:03
S36	54	("2734154"   "4034468"   "4034469"   "4254431"   "4299715"   "4323914"   "4398975"   "4435611"   "4466483"   "4473113"   "4607277"   "4806111"   "4915167"   "4966142"   "5011787"   "5031308"   "5037312"   "5056706"   "5071787"   "5074947"   "5086558"   "5097387"   "5131582"   "5148141"   "5148265"   "5148266"   "5164566"   "5170930"   "5196371"   "5198189"   "5223747"   "5237130"   "5323294"   "5325265"   "5328087"   "5445308"   "5455390"   "5459352"   "5542602"   "5553769"   "5557501"   "5561590"   "5572404"   "5651179"   "5658831"   "5688721"   "5720100"   "5808874"   "5819406"   "5920125"   "5975408"   "6000127"). PN. OR ("6202298"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/22 14:10

S37	31	("4604644"   "4999699"   "5007163"   "5170930"   "5391514").PN. OR ("5553769").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/22 14:18
S38	10	("20020109227"   "4893172"   "5553769"   "5796590"   "6133978"   "6204163"   "6208027"   "6407451"   "6495926"). PN. OR ("6664625"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/22 14:19
S39	73	("4142286"   "5051339"   "5164818"   "5189507"   "5255431"   "5337219"   "5403671"   "5435482"   "5442852"   "5453581"   "5463191"   "5477933"). PN. OR ("5796590"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/22 14:34
S40	161	S36 or S37 or S38 or S39	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 14:34
S41	19	S40 and (signal or ground or power) near50 (vias or (contact near10 pad))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 14:37
S42	14	("3872583"   "4646435"   "5222014"   "5237743"   "5473510"   "5477933"   "5541450"   "5553769"). PN. OR ("5808875"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/22 14:38

S43	75	("4092697"   "4141135"   "4156458"   "4161701"   "4180414"   "4295183"   "4322778"   "4349862"   "4498530"   "4612601"   "4617730"   "4639829"   "4652977"   "4698663"   "4717591"   "4729060"   "4740866"   "4758926"   "4926241"   "4942076"). PN. OR ("5325265"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/22 15:58
S44	396	(mount\$3 or connect\$3) and integrated and circuit and package and substrate and (permanent or remov\$3) with solder with mask	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 17:12
S45	58	S44 and (signal or ground or power) near50 vias	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 16:09
S46	58	S44 and (signal or ground or power) near50 via	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 16:09

S47	19	("2427144"   "4048438"   "4177519"   "4383363"   "4949155"   "5243142"   "5535101"   "5600103"   "5736681"   "5737833"   "5758413"   "5798563"   "5870289"   "5909010"   "5979044"   "6010769"   "6052287"   "6075710"). PN. OR ("6915566"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/22 16:20
S48	91	("5068714"   "5406459"   "5407864"   "5611884"). PN. OR ("5870289"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/22 16:26
S49	45	("3372310"   "3671812"   "3991347"   "4107760"   "4122508"   "4291364"   "4315300"   "4339628"   "4375290"   "4423468"   "4549200"   "4580193"   "4619316"   "4674004"   "4730232"   "4739444"   "4771366"   "4782381"   "4783695"   "4830264"   "4831433"   "4835344"   "4838475"   "4841355"   "4868634"   "4956746"   "5023754"   "5027505"   "5057971"   "5101322"). PN. OR ("5208729"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/22 17:09
S50	760	integrated with circuit with package with (power or ground or signal)near50(vias or plane or bar)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 17:26

S51	25	S50 with solder near20(ball or mask)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 17:26
S52	1747	integrated with circuit with package with (power or ground or signal)near50(vias or connect\$3 or bar)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 17:26
S53	40	S52 with solder near20(ball or mask)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/22 17:26
S54	4	("2001/0013654").URPN.	USPAT	OR	ON	2005/09/22 17:27